

Part Number: WP57EGW

High Efficiency Red  
Green

### Features

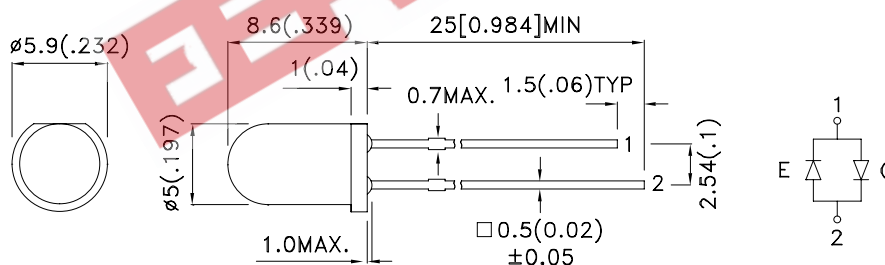
- LOW POWER CONSUMPTION.
- I.C. COMPATIBLE.
- LONG LIFE - SOLID STATE RELIABILITY.
- RoHS COMPLIANT.

### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25 (0.01)$  unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP57EGW	High Efficiency Red (GaAsP/GaP)	WHITE DIFFUSED	10	30	60°
	Green (GaP)		10	20	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Green	627 565		nm	I <sub>F</sub> =20mA
λD [1]	Dominant Wavelength	High Efficiency Red Green	625 568		nm	I <sub>F</sub> =20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Green	45 30		nm	I <sub>F</sub> =20mA
C	Capacitance	High Efficiency Red Green	15 15		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub> [2]	Forward Voltage	High Efficiency Red Green	2 2.2	2.5 2.5	V	I <sub>F</sub> =20mA

Notes:

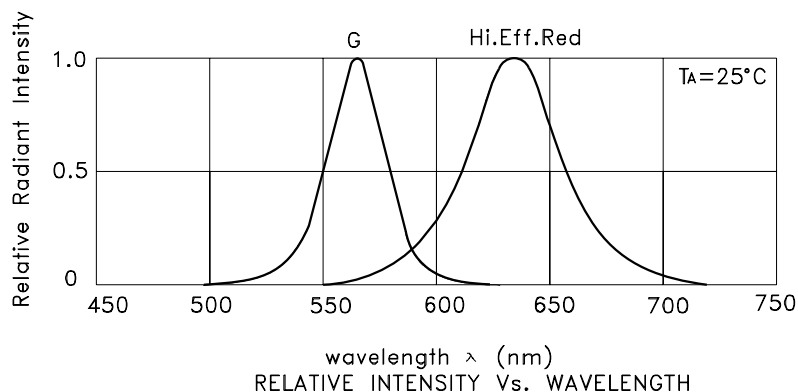
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

## Absolute Maximum Ratings at TA=25°C

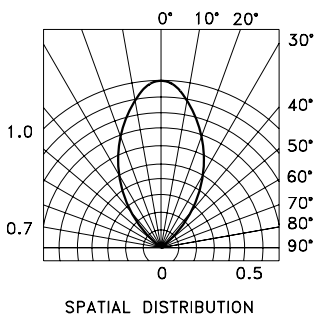
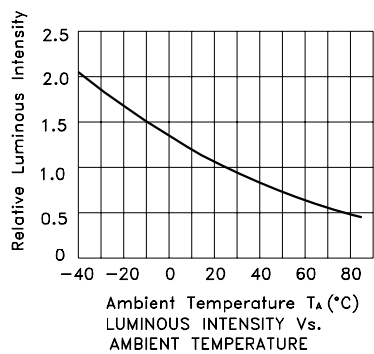
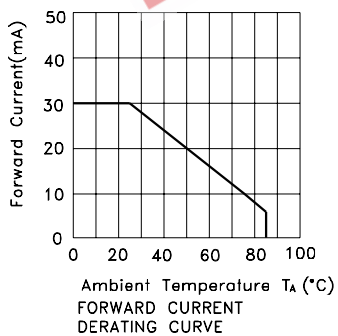
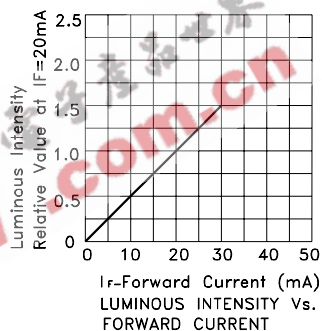
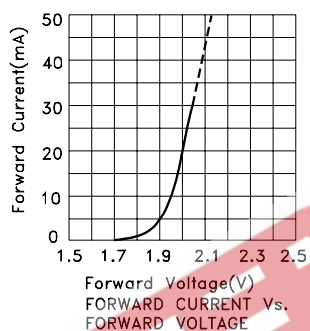
Parameter	High Efficiency Red	Green	Units
Power dissipation	75	62.5	mW
DC Forward Current	30	25	mA
Peak Forward Current [1]	160	140	mA
Operating / Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.

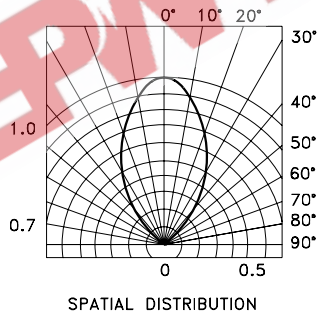
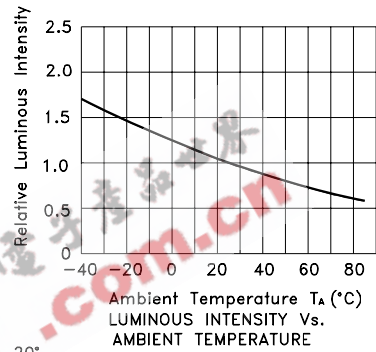
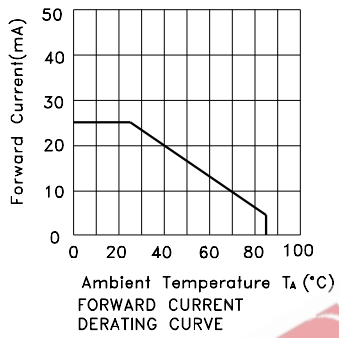
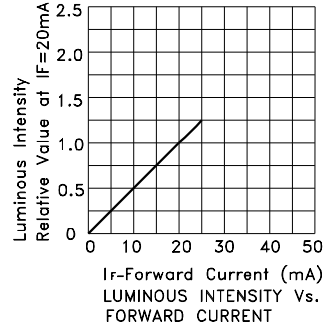
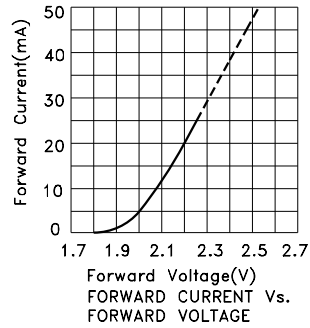


## WP57EGW High Efficiency Red



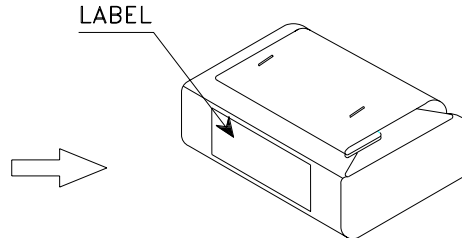
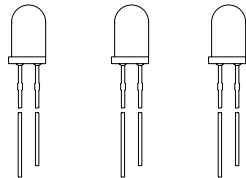
# Kingbright

## Green



PACKING & LABEL SPECIFICATIONS

WP57EGW

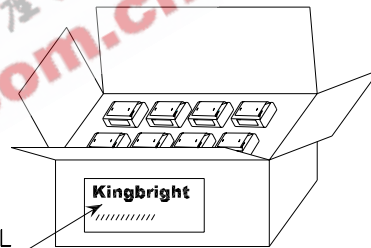


500PCS / BAG




32K / 9# BOX

OUTSIDE LABEL



OUTSIDE LABEL

16K / 5# BOX

<h1>Kingbright</h1>				
Q.C.	<table border="1"> <tr> <td>QC</td> </tr> <tr> <td>XX XX XX</td> </tr> <tr> <td>PASSED</td> </tr> </table>	QC	XX XX XX	PASSED
QC				
XX XX XX				
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TYPE NO : WP57xxx				
QUANTITY : 500 pcs				
S/N : XX	CODE: XX			
LOT NO : 				
RoHS Compliant				

## LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

(Fig. 1)

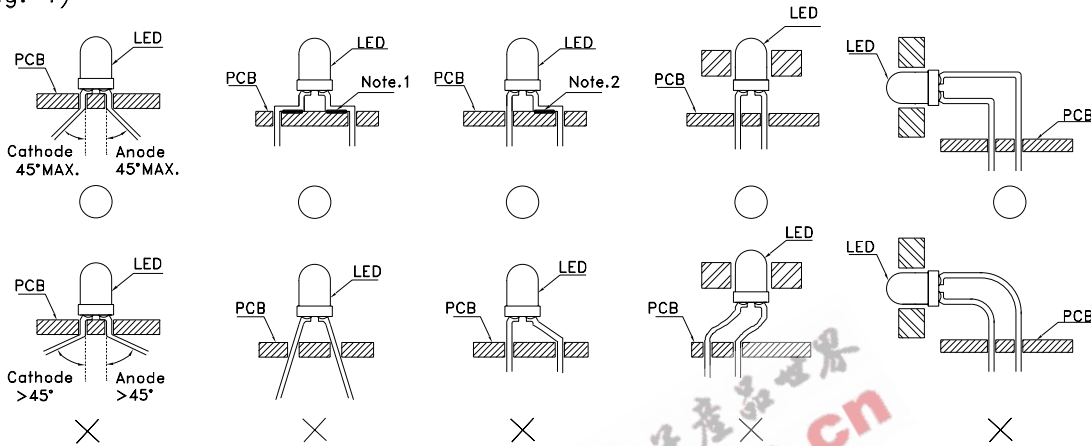


Fig.1

“○” Correct mounting method “×” Incorrect mounting method

Note 1-2 : Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit.

(Fig. 2)

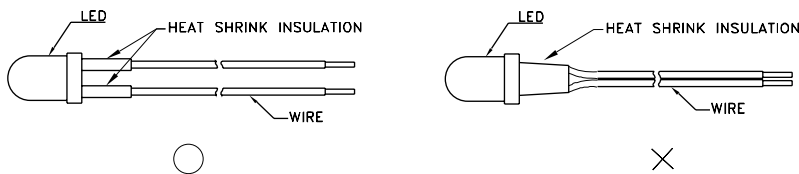


Fig. 2

3. Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.

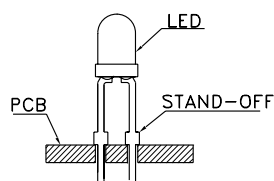


Fig. 3

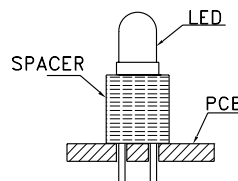


Fig. 4

## LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)

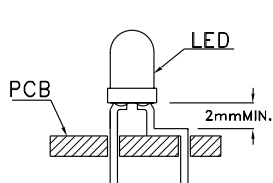


Fig. 5

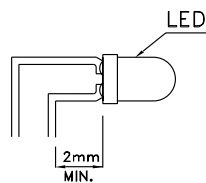


Fig. 6

2. Lead forming or bending must be performed before soldering, never during or after Soldering.
3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
5. Do not bend the leads more than twice. (Fig. 8)

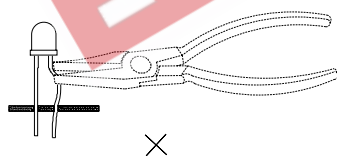


Fig. 7

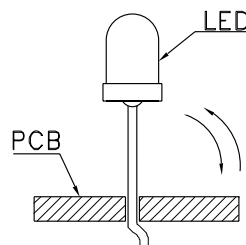


Fig. 8

6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.

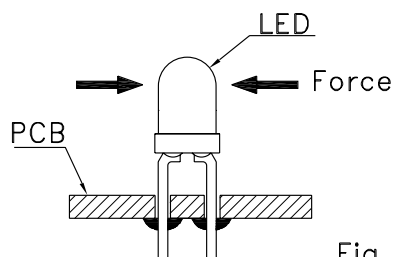


Fig. 9